


記號 MARK	設 變 內 容 MODIFICATION	日 期 DATE	修 改 DRAW	核 准 APPROVE
	尺寸變更	2014/11/21	MAY	JASON

NOTE:

1.MATERIAL

1.1.HOUSING: HIGH TEMP :UL94V-0

1.2.CONTACT: C2680 T=0.25

1.3.SHELL: SPCC-SD T=0.30

2. FINISH:

2.1 CONTACT:

GOLD FLASH PLATING ON CONTACT AREA.

80u" MIN TIN PLATING ON SOLDER TAIL AREA,

50u" MIN. NICKEL UNDERPLATING OVERALL,

2.2. SHELL:

80u" NICKEL MIN PLATING OVERALL

3. RECOMMENDED PCB THICKNESS : 1.60mm

4. APPLIED TO WAVE SOLDERING PROCESS

5. MADE  DIMENSIONS NEED BE MEASURED IN FAI.

6.1 ELECTRICAL:

VOLTAGE RATING: 30VAC RMS;

CURRENT RATING: 1 AMP MIN;

CONTACT RESISTANCE: 30 MINIOHMS MAX;

INSULATION RESISTANCE: 1000MEGOHMS MIN 500VDC;

DIELECTRIC WITHSTANDING VOLTAGE:

UNMATED CONTACT 500VAC RMS 60MHZ 1MIN;

6.2.MECHANICAL:

CONTACT RETENTION FORCE:5N MIN

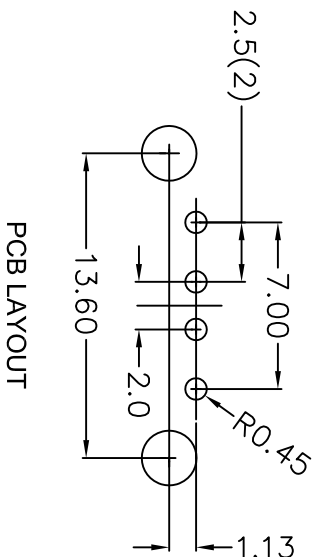
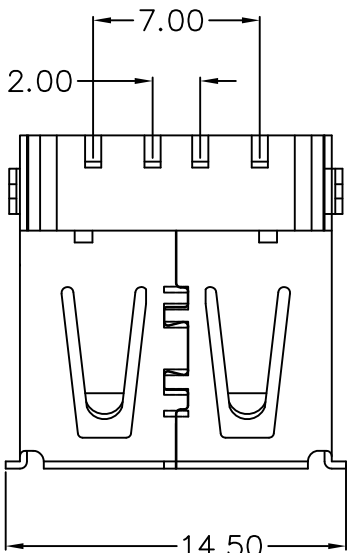
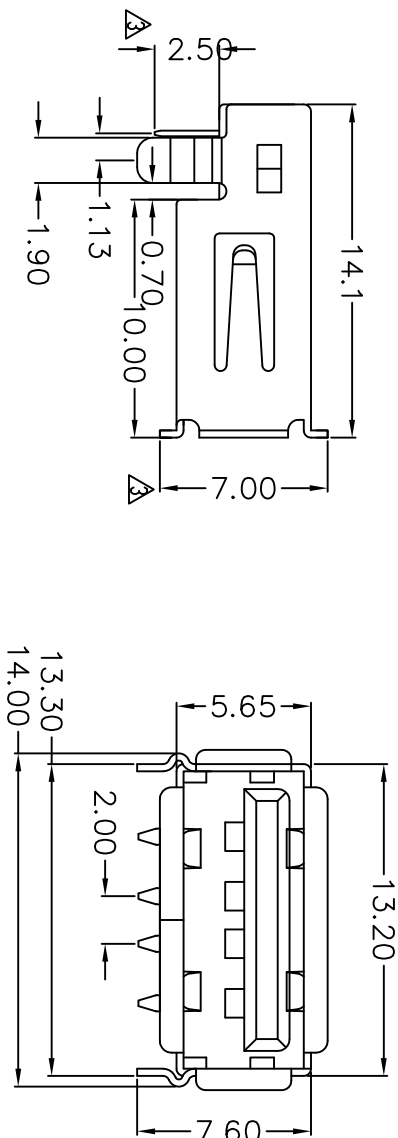
MATING FORCE: 35N MAX

UNMATING FORCE: 10N MIN

OPERATING LIFE:1500CYCKES

6.3.ENVIRONMENTAL:

OPERATING TEMPERATURE: -45°C TO 75°C.



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UNLESS OTHERWISE SPECIFIED TOLERANCES ARE			
.x	±0.30	繪 圖 / 日 期	MAY 2014.11.21
.xx	±0.20	審 核 / 日 期	SHARON 2014.11.21
.xxx	±0.10	Check By/Date	JASON 2014.11.21
.x"	±3.0"	批 準 / 日 期	JASON 2014.11.21
.xx"	±2.0"	App. By/Date	JASON 2014.11.21
.xxx"	±1.0"		
單位	名稱	頁 次	角 法
MM	USB A/F DIP 90度沉板打K脚有边	1/1	PROJ.
比例	料號	版 本	REV.
1:1	HUSB-FA4-RFD-10	03	